

METHODS OF FORMING CONDUCTIVE PATTERNS USING BARRIER
LAYERS

ABSTRACT

5 A conductive pattern can be formed in a mold layer by removing a portion of a
barrier layer outside an intaglio pattern in a mold layer to expose an upper surface of
the mold layer and avoiding removing a portion of the barrier layer on the intaglio
pattern. A conductive layer can be formed on the portion of the barrier layer on the
intaglio pattern and on the upper surface of the mold layer. The conductive layer can
10 be removed from the upper surface of the mold layer.